

ABSTRACT OF THE DISCLOSURE

A method of making a semiconductor device is provided. The method includes the following steps. First, a semiconductor
10 chip is mounted on a lower conductor, with first solder material applied between the chip and the lower conductor. Then, an upper conductor is placed on the chip, with second solder material applied between the chip and the upper conductor. Then, the first and the second solder materials are heated up
15 beyond their respective melting points. Finally, the first and the second solder materials are allowed to cool down, so that the first solder material solidifies earlier than the second solder material.